

Title (en)

Method for manufacturing thin boards, especially parqueting blocks

Title (de)

Verfahren zur Herstellung von dünnen Brettern, insbesondere Parkettlamellen

Title (fr)

Procédé pour tranches des planches minces, en particulier des lamelles de parquet

Publication

EP 0732180 B1 20000719 (DE)

Application

EP 96103619 A 19960308

Priority

DE 19509653 A 19950317

Abstract (en)

[origin: EP0732180A2] The method uses a series of cutting devices, which repeatedly cut thin strips from squared timber. The thickness of the thin strips cut by each individual cutting device (1) is determined separately. The actual detected value is compared to a reference value for the strips cut by this device. The variation generates a signal, which is used to correct the blade setting for subsequent cutting. The actual thickness of a strip is calculated as a differential of the thickness of the remaining timber (5) before and after cutting.

IPC 1-7

B27L 5/06

IPC 8 full level

B27L 5/06 (2006.01)

CPC (source: EP)

B27L 5/06 (2013.01)

Citation (examination)

JP H05131401 A 19930528 - MARUNAKA TEKKOSHO INC

Cited by

EP2243606B1

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EP 0732180 A2 19960918; EP 0732180 A3 19970115; EP 0732180 B1 20000719; AT E194791 T1 20000815; CA 2171508 A1 19960918; DE 19509653 C1 19960523; DE 59605614 D1 20000824; JP H0985712 A 19970331

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EP 96103619 A 19960308; AT 96103619 T 19960308; CA 2171508 A 19960311; DE 19509653 A 19950317; DE 59605614 T 19960308; JP 8873996 A 19960318